

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-107046  
 (43)Date of publication of application : 22.04.1997

(51)Int.Cl. H01L 23/12

(21)Application number : 07-262818  
 (22)Date of filing : 11.10.1995

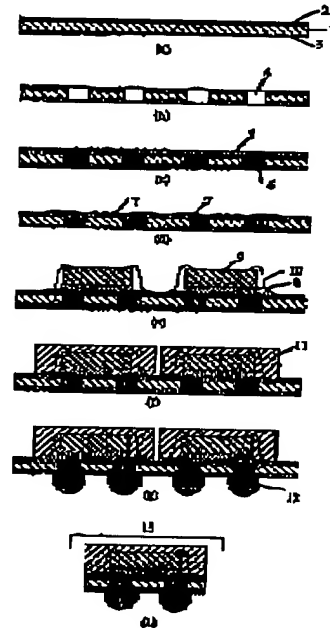
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## (54) SEMICONDUCTOR PACKAGE

## (57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor package adaptable for reducing the size and increasing the density of the package.

SOLUTION: A semiconductor package has a board for mounting a semiconductor chip 9 on an insulation board, interconnection pattern 7 electrically connected to semiconductor chip electrodes formed on one side of the board, external connection terminals 12 formed on the other side of the board 1, and layer interconnection 6 connecting the pattern 7 to the terminals 12. The substrate is formed so that the end part of the pattern connected to the interconnection 6 may be within a plane region exposed of the interconnection 6.



## LEGAL STATUS

[Date of request for examination]  
 [Date of sending the examiner's decision of rejection]  
 [Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]  
 [Date of final disposal for application]  
 [Patent number]  
 [Date of registration]  
 [Number of appeal against examiner's decision of rejection]  
 [Date of requesting appeal against examiner's decision of rejection]  
 [Date of extinction of right]

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